## nexperia

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier		User Part Number					
Nexperia B.V.		PMEG2002AESF					
Name of Laboratory Assembly reliability labs		Part Description					
		Nexperia DHAM	Schottky				
		BD					
Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects	
	TEST Pre- and Post-Stress						
# 1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
		MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet					
# 5	Bias	reverse voltage <sup>[1]</sup>	1000 hours	36	2880	0	
# 7	<b>TC</b> Temperature Cycling	JESD22-A104 -40 °C to 125°C	1000 cycles	36	2880	0	
# 8	<b>AC</b> Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	n.a.	n.a.	n.a.	
# 9	<b>H3TRB</b> High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage <sup>[1], [2]</sup>	1000 hours	n.a.	n.a.	n.a.	
# 10	<b>IOL</b> Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj$ = 100 °C for 15000 cycles	1000 hours	36	2880	0	
	RSH	JESD22-A111					
# 20	Resistance to Solder Heat	260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.	
# 21	<b>SD</b> Solderability	J-STD-002		36	360	0	

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab 1	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM S	Schottky	2880	0	1.47	6.78E+08

© 2022 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.